

## **Advancements in Tracking Techniques for Future Circular Collider Experiments**





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## Machine luminosity at e+e- colliders





### Requirements of tracking system for an experiment at a leptonic collider

### **Central tracker system:**

- ➢ state-of-the-art momentum and angular resolution for charged particles;
- ➢ B field limited to ≈ 2 T to contain the vertical emittance at Z pole. Large racking radius needed to improve momentum resolution.
- ➢ High transparency required given typical momenta in Z, H decays (far form the asymptotic limit where the Multiple Scattering contribution is negligible).
- $\triangleright$  Particle ID is a valuable additional ability.

## **Vertexing:**

- $\triangleright$  excellent b- and c-tagging capabilities : few µm precision for charged particle origin;
- $\triangleright$  small pitch, thin layers, limited cooling, first layer as close as possible to IP.

## **Challenges:**

 $\triangleright$  Physics event rates up to 100 kHz (at Z pole)  $\rightarrow$  strong requirements on sub-detectors and DAQ systems

## Detector concepts for experiments at FCC-ee

**IDEA** 

Instrumented return voke **Double Readout Calorimeter** 



- Well established design  $\bullet$ 
	- ILC -> CLIC detector -> CLD  $\bullet$
- Full Si vtx + tracker;
- **CALICE-like calorimetry;**
- Large coil, muon system
- Engineering still needed for operation with  $\bullet$ continuous beam (no power pulsing)
	- Cooling of Si-sensors & calorimeters
- Possible detector optimizations
	- $\sigma_{\rm p}/p$ ,  $\sigma_{\rm E}/E$
	- PID ( $O(10 \text{ ps})$  timing and/or RICH)?
	-



- - But still ~15y history
- Si vtx detector; ultra light drift chamber w powerful PID; compact, light coil;
- Monolithic dual readout calorimeter;
	- Possibly augmented by crystal ECAL
- **Muon system**
- Very active community
	- Prototype designs, test beam campaigns, ...



- Si vtx det., ultra light drift chamber (or Si)
- High granularity Noble Liquid ECAL as core
	- Pb/W+LAr (or denser W+LKr)
- **CALICE-like or TileCal-like HCAL:**
- Coil inside same cryostat as LAr, outside ECAL
- Muon system.
- Very active Noble Liquid R&D team
	- Readout electrodes, feed-throughs, electronics, light cryostat, ...
	- Software & performance studies

## The IDEA detector at e<sup>+</sup>e<sup>-</sup> colliders (1)

### **Innovative Detector for E+e- Accelerator**

**IDEA** consists of:

- a silicon pixel vertex detector
- a large-volume extremelylight **drift chamber**
- surrounded by a layer of silicon micro-strip detectors
- a thin low-mass superconducting solenoid coil<sup>9</sup>
- a preshower detector based on **µ-WELL technology**
- a dual read-out calorimeter
- muon chambers inside the magnet return yoke, based on **µ-WELL technology**



Low field detector solenoid to maximize luminosity (to contain the vertical emittance at Z pole).

- $\rightarrow$  optimized at 2 T
- → large tracking radius needed to recover momentum resolution

## Vertex detector Insubria U.+ Milano U.

### **ARCADIA prototype**

### Technology: Depleted Monolithic Active Pixel Sensors (DMAPS):

- $\geq 25$  x 25 um<sup>2</sup> pixel size for hit resolution  $\sim 3$  um
- $5 \mu m$  shown by ALICE ITS (30 mm pixels)
- $\triangleright$  prototype with thickness  $\sim$  200  $\mu$ m down to 50 $\mu$ m
- $\triangleright$  matrix 512x512
- $\triangleright$  low power consumption (< 20 mW/cm<sup>2</sup>)

### Tests of different design options:

• IV and CV measurements of test-structures from the first and second production run: proven functionality, stable operation at full depletion, and good agreement with TCAD simulations  $A$   $A$   $2^{nd}$  iteration prototype is working and will



## be tested soon at a test beam area



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### Silicon medium and outer tracker KIT+UK+IHEP+INFN

### ATLASPIX3 modules: a full-size system on chip, targeting the medium and outer tracker

- ➢ quad module, inspired by ATLAS ITk pixels
- $\triangleright$  pixel size 50×150 µm<sup>2</sup> (25×165 µm<sup>2</sup> small size prototypes delivered)
- ➢ reticle size 20×21 mm<sup>2</sup>
- $\triangleright$  TSI 180 nm process on 200 Ωcm substrate
- $\geq$  132 columns of 372 pixels

### Power consumption:

- $\triangleright$  ATLASPIX3 power consumption 150 mW/cm<sup>2</sup>
- $\geq 600$  mW/chip  $\rightarrow$  2.4 W/module  $\rightarrow$  total FE power 130 kW
- $\triangleright$  additional power for on detector aggregation and de-randomizations  $\sim$  2W/link



Complete system consists of 900'000 cm<sup>2</sup> area / 4 cm<sup>2</sup> chip = 225k chips (56k quad-modules):

- ➢ aggregation of several modules for data and services distribution is essential
- $\geq$  inner tracker will be 5-10% of this

### Data rate constrained by the inner tracker:

- $\triangleright$  average rate 10<sup>-4</sup> 10<sup>-3</sup> particles cm<sup>-2</sup> event<sup>-1</sup> at Z peak
- ➢ assuming 2 hits/particle, 96 bits/hit for ATLASPIX3
- See A. Andreazza talk for details ➢ 640 Mbps link/quad-module (assuming local module aggregation) provides ample operational margin
- ➢ 16 modules can be arranged into 10 Gbps fast links: 3.5k links
- $\triangleright$  can also assume 100 Gbps links will be available: 350 links

## Design features of the IDEA Drift Chamber

### INFN Bari and Lecce, IHEP + contributions from UCL, NWU and FSU

For the purpose of tracking and ID at low and medium momenta mostly for heavy flavour and Higgs decays, the IDEA drift chamber is designed to cope with:

- ➢ transparency against multiple scattering, more relevant than asymptotic resolution
- $\triangleright$  a high precision momentum measurement
- an excellent particle identification and separation

Particle momentum range far from the asymptotic limit where MS is negligible



## The Drift Chamber

### The DCH is:

- ➢ a unique-volume, high granularity, fully stereo, low-mass cylindrical
- gas: He 90%  $iC_4H_{10}$  10%
- $\triangleright$  inner radius R<sub>in</sub> = 0.35m, outer radius R<sub>out</sub> = 2m
- $\triangleright$  length L = 4m
- drift length  $\sim$ 1 cm
- $\triangleright$  drift time ~150ns
- $\triangleright$   $\sigma_{xy}$  < 100  $\mu$ m,  $\sigma_{z}$  < 1 mm
- $\geq 12 \div 14.5$  mm wide square cells, 5 : 1 field to sense wires ratio
- ➢ 112 co-axial layers, at alternating-sign stereo angles, arranged in 24 identical azimuthal sectors, with frontend electronics
- ➢ 343968 wires in total:

sense vires: 20  $\mu$ m diameter W(Au) = > 56448 wires field wires: 40  $\mu$ m diameter Al(Ag) = > 229056 wires f. and g. wires: 50  $\mu$ m diameter Al(Ag) = > 58464 wires

 $\triangleright$  the wire net created by the combination of + and orientation generates a more uniform equipotential surface  $\rightarrow$  better E-field isotropy and smaller ExB asymmetries )



a large number of wires requires a non standard wiring procedure and needs a feed-through-less wiring system  $\rightarrow$  a novel wiring procedure developed for the construction of the ultra-light MEG-II drift chamber



## The Drift Chamber: Cluster Counting/Timing and PID

Principle: In He based gas mixtures the signals from each ionization act can be spread in time to few ns. With the help of a fast read-out electronics they can be identified efficiently.

 $\triangleright$  By counting the number of ionization acts per unit length ( $dN/dx$ ), it is possible to identify the particles (P.Id.) with a better resolution w.r.t the dE/dx method.



• collect signal and identify peaks

• record the time of arrival of electrons generated in every ionisation cluster

• reconstruct the trajectory at the most likely position

 $\triangleright$  Landau distribution of dE/dx originated by the mixing of primary and secondary ionizations, has large fluctuations and limits separation power of PID  $\rightarrow$  primary ionization is a Poisson process, has small fluctuations

 $\triangleright$  The cluster counting is based on replacing the measurement of an ANALOG information (the [truncated] mean dE/dX ) with a DIGITAL one, the number of ionisation clusters per unit length:

**dE/dx**: truncated mean cut (70-80%), with a 2m track at 1 atm give  $\sigma \approx 4.3\%$ 

 $dN_{cl}/dx$ : for He/iC<sub>4</sub>H<sub>10</sub>=90/10 and a 2m track gives  $\sigma_{dNcl/dx}$  **/(dN**<sub>cl</sub>**/dx)** < 2.0%

## The Drift Chamber: Cluster Counting/Timing and PID

# of

sigma

10

9

8

**Analitic** 

calculations

e/u  $\mu/\tilde{\pi}$ 

 $K/\pi$ 

Particle Separation (dE/dx vs dN/dx)

 $dN/dx$ 

 $dE/dx$ 

- Analitic calculations: Expected excellent K/ $\pi$ separation over the entire range except 0.85<p<1.05 GeV (blue lines)
- $\triangleright$  Simulation with Garfield + + and with the Garfield model ported in GEANT4:
	- ➢ the particle separation, both with dE/dx and with  $dN_{cl}/dx$ , in GEANT4 found considerably worse than in Garfield
	- $\triangleright$  the dN<sub>cl</sub>/dx Fermi plateau with respect to steeper slope
	- finding answers by using real data from beam tests at CERN in 2021 and 2022, and 2024



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outlet as manifol

box

### Data reduction and pre-processing of drift chamber signals

Issue: with about 60000 drift cells, assuming to digitise the signal at 12 bits and 2 GS/s, a throughput of about 1 Tb/s is hardly sustainable by modern equipment  $\rightarrow$  is necessary to transfer all the data.

- with the cluster counting algorithms, by transferring only time and amplitude of each electron peak, these rates are reduced to about 60 Gb/s, resulting in a data reduction factor of more than one order of magnitude.
- Applying the cluster counting technique on FPGAs in real time has two main objectives:
	- 1. reduce transferred data
	- 2. reduce stored information
- A secondary advantage that allows us to reduce CPU usage during data analysis as the waveforms have already been analyzed in real time, saving only the necessary information

The objective of the new project is to implement, on a single FPGA, cluster counting algorithms for the parallel preprocessing of as many channels as possible in order to reduce the costs and complexity of the system and gain flexibility in determining the proximity correlations between hit cells for track segment search and for triggering purposes.

- For this purpose a card with multichannel reading is under development, testing different digitizers:
	- TEXAS INSTRUMENTS ADC32RF45 → implementation of cluster counting almost complete
	- CAEN digitzer
	- NALU SCIENTIFIC ASoC $v3 \rightarrow$  test with native acquisition program and then implementation of the cluster counting





## Silicon wrapper **INFN** Genova

### In IDEA concept, tracking and PID provided by the DCH  $(+ VTX + \text{medium and outer T})$

- Silicon wrapper for precise polar angle measurement
- Good K-p separation from dE/dx except for  $p \sim 1$  GeV
- Baseline: ATLASPIX3 modules **BUT**
- LGAD (Low-Gain Avalanche Diodes) with RSD (Resistive Silicon Detectors) technology are a possible option:
	- ➢ TOF with excellent time resolution
	- Position from pixel-like geometry or charge sharing resistive-layer design



#### Particle Separation (dE/dx vs dN/dx)



Reconstruction of the position from the signal distribution between contiguous electrodes

Need to show that LGAD could be produced with acceptable cost

- $\triangleright$  Technology developed by INFN Turin group, production by FBK
- External funding also (ERC, PRIN)

## Muon detectors for IDEA: guiding principles

### INFN Frascati, Ferrara, CERN

Future colliders experiments require extremely large muon detectors :

- $\triangleright$  ~10000 m<sup>2</sup> in the barrel
- $\geq 3$ -5000 m<sup>2</sup> in the endcap
- $\geq 300$  m<sup>2</sup> in the very forward region



## The  $\mu$ -RWELL detector schema

### R&D on  $\mu$ -RWELL technology mainly motivated by the wish of improving:

- the stability under heavy irradiation (discharge suppression)
- the construction technology (simplifying the assembly)
- $\checkmark$  the technology transfer to industry (mass production)

The μ-RWELL is a Micro Pattern Gaseous Detector (MPGD) composed of only two elements: the μ-RWELL\_PCB and the cathode.



- **<sup>1</sup>** A WELL patterned kapton foil acting as amplification stage (GEM-like)
- a resisitive DLC layer (Diamond Like Carbon) for discharge suppression w/surface resistivity ~ 50÷100 MΩ/sq





Applying a suitable voltage between the top Cu-layer and the DLC the WELL acts as a multiplication channell for the ionization produced in the conversion/drift gas gap.



**Test beam at CERN with** µ-RWELL prototypes with

- 40cm long strips
- 0.4 mm strip pitch
- 1D readout

M.Abbrescia

### -RWELL test beam results and technology transfer





**Technology** transfer with ELTOS/CERN: flow chart

# IStituto Nazionale di Fisica Nucleare

#### Responsibility:

- Detector design (GERBER);
- **Link with FLTOS**
- Link with CERN-Rui
- Quality Control detector
- DLC Machine managment  $( > 2023)$

### Filos

#### Responsibility:

- PCB RWELL production
- Cathode production
- DLC+PCB RWELL coupling

# CERN

#### Responsibility:

- PCB RWELL finalization
- Hot Electrical Cleaning
- Detector closure

### Simulation and performance of the IDEA tracking system

A full standalone Geant4 (and partially DD4HEP) simulation of the Silicon Vertex (and Si wrapper), DriftChamber, DR Calorimeter and Muon Preshower







## Summary/Conclusions

### Advanced R&D effort on tracking detectors:

- $\triangleright$  vertex pixel detector, based on ARCADIA
- ➢ silicon medium and outer tracker, based on ATLASPIX3
- ➢ silicon wrapper, based on ATLASPIX3 (LGAD under evaluation)
- $\triangleright$  drift chamber design and cluster counting study, sinergy with MEG2
- $\triangleright$  muon chambers, synergy with LHCb upgrades

### Plenty of areas for collaboration:

- ➢ detector design, construction, beam test, performance
- $\triangleright$  local and global reconstruction, full simulation
- $\triangleright$  physics performance and impact
- $\triangleright$  etc.

### Effort to build international collaboration on going (in some areas well advanced) and to be enforced

### Manpower, funding under continuous discussion

## Backup

## Machine luminosity for physics at e<sup>+</sup>e colliders





Higgs factory:

- $\blacksquare$  10<sup>6</sup> e<sup>+</sup>e<sup>-</sup>  $\rightarrow$  HZ
- ➢ EW & Top factory:
	- $3x10^{12}$  e<sup>+</sup>e<sup>-</sup>  $\rightarrow$  Z
	- $\blacksquare$  10<sup>8</sup> e+e<sup>-</sup>  $\rightarrow$  W<sup>+</sup>W<sup>-</sup>
	- 10<sup>6</sup>  $e^+e^- \rightarrow tt$

### ➢ Flavor factory:

- $5x10^{12}$  e+e-  $\rightarrow$  bb, cc
- $10^{11}$  e+e-  $\rightarrow$   $\tau$ + $\tau$ -



**EWK and Heavy Flavour**

**Heavy** 

**Flavou** 

### Physics requirements: Higgs, EWK and Heavy Flavour

### Tracking:

- Momentum resolution for Z recoil (and  $H\rightarrow\mu\mu$ )
	- Comparatively low momenta involved  $\rightarrow$  transparency is important
- Vertex resolution/transparency to separate g, c, b,  $\tau$  final states

### Calorimetry:

- Jet-jet invariant mass resolution to separate W, Z, H in 2 jets
- **Good**  $\pi^0$  ID for  $\tau$  and HF reconstruction

### ➢ EWK:

- Extreme definition of detector acceptance
- **Extreme EM resolution (crystals) under study** 
	- Improved  $\pi^0$  reconstruction
	- Physics with radiative return

### Heavy Flavour:

PID to accurately classify final states and flavor tagging

# The IDEA detector at e<sup>+</sup>e<sup>-</sup> colliders (2)



- Tracking coverage  $\rightarrow$  150 mrad  $\rightarrow$  No material in front of luminometer
- Calorimetry  $\rightarrow$  100 mrad

#### Goals of the IDEA tracking system:

- to preserve the momentum resolution for Z recoil (and  $H\rightarrow\mu\mu$ )
	- comparatively low momenta involved  $\rightarrow$  transparency is important
- to preserve the vertex resolution/transparency to separate g, c, b,  $\tau$  final states

### Silicon medium and outer tracker



See F. Palla talk for details

Intermediate Tracker Barrel At 13 cm radius

22 staves of 8 modules each.

Lightweight reticular support structure (ALICE/Belle-II like)

> Outer Tracker Barrel At 31.5 cm radius

51 staves of 16 modules each

Lightweight reticular support structure (ALICE/Belle-II like)

## Design features: the Drift Chamber

### **Novel approach at construction technique of high granularity and high transparency Drift Chambers**

Based on the MEG-II DCH new construction technique the IDEA DCH can meet these goals:

- Gas containment wire support functions separation: allows to reduce material to  $\approx 10^{-3}$  X<sub>0</sub> for the inner cylinder and to a few x 10<sup>-2</sup>  $X_0$  for the end-plates, including FEE, HV supply and signal cables
- Feed-through-less wiring:



allows to increase chamber granularity and field/sense wire ratio to reduce multiple scattering and total tension on end plates due to wires by using thinner wires



# Chamber Layout (the IDEA drift chamber)





## Wire Layout (the IDEA drift chamber)

- $\Box$  112 co-axial layers (grouped in 14 superlayers of 8 layers each) of para-axial wires in 24 azimuthal sectors;
- $\Box$  stereo angles from  $\pm$ 43 mrad to  $\pm$ 223 mrad;
- $\Box$  rotational hyperboloid for each layer
- $\Box$  192 (at inner layer), 816 (at outer layer) square drift cells  $(16$  per sector);
- $\Box$  cell size ranging from 11.8 mm at the innermost layer, to 14.9 mm at the outermost one;
- $\Box$  ratio of field wires to sense wires = 5 : 1;
- $\Box$  56 448 sense wires 284 256 field wires 2 016 guard wires:
- $\Box$  sense wires 20 µm diameter gold plated Mo (30 g tension);
- $\Box$  field and guard wires, 40 and 50  $\mu$ m diameter silver plated Al  $(30 g)$ ;
- $\Box$  total wire tension 10 Ton.

## Mechanical construction scheme

**stress**

#### **Gas containment**

Gas vessel can freely deform without affecting the internal wire position and mech. tension.



#### **Wire support**

Wire support structure not subject to differential pressure can be light and feed-through-less.



### **Plan for 2023/2024:**



### **Static solution**



**350 MPa**

**On going:** Finite element analysis in collaboration with a

company (EnginSoft) and Politecnico Un. in Turin.

**End plates: 4-ply orthotropic (0-90-90-0) HM M30S 53 ET443 51% 60 μm/ply - 0.0053 g/cm<sup>2</sup> (0.021 g/cm<sup>2</sup> total)**

#### **Analogy with MEG2 drift chamber Wire tension recovery scheme**



electrostatic stability and to validate the proposed tension recovery scheme of the endplates. • construct a full-size prototype (4m long) to test different wire choices and the relative

### Gas Vessel (tentative procedure)

### ❑ **End-plate profile optimization**

- ➢ **Use isotropic material (1 mm thick Aluminum) solid rotational plates + inner cylinder (ideal joints)**
- ➢ **Assume infinitely rigid outer cylinder**
- ➢ **Parameterize geometry by:**
	- **constraining inner cylinder radius**
	- **constraining inner cylinder length**
	- **constraining outer cylinder radius**
	- **varying middle point of a 3 point-spline profile for the end plates**
- ➢ **Optimize dynamic properties:**
	- **minimum stress at inner boundary**
	- **minimum of maximum stress**
	- **maximum safety factor**
- ➢ **Replace isotropic material with light composite material**
- ➢ **Detailed FEM analysis**
- ❑ **Solve buckling instabilities**
- ❑ **Measure mechanical properties of chosen material**
- ❑ **Build a scale model and characterize it**

## Design features: the Drift Chamber

### **Novel approach at construction technique of high granularity and high transparency Drift Chambers**

### The solution adopted for MEG II:

- end-plates numerically machined from solid Aluminum (mechanical support only);
- <sup>◼</sup> Field, Sense and Guard wires placed azimuthally by a Wiring Robot with better than one wire diameter accuracy;
- wire PC board layers (green) radially spaced by numerically machined peek spacers (red) (*accuracy < 20 µm*);
- wire tension defined by homogeneous winding and wire elongation (*ΔL = 100μm corresponds to ≈ 0.5 g*);
- Drift Chamber assembly done on a 3D digital measuring table;
- build up of layers continuously checked and corrected during assembly;
- End-plate gas sealing done with glue.



**(~ 12 wires/cm<sup>2</sup> ) impossible to be built with a conventional technique based on feedthrough:**



# Cluster counting/timing performance

From the ordered sequence of the electrons arrival times, considering the average time separation between clusters and their time spread due to diffusion, reconstruct the most probable sequence of clusters drift times:

$$
\begin{cases} t_i^{cl} \\ \frac{dE}{dx} \end{cases}
$$

$$
\frac{S_{dE/dx}}{(dE/dx)} = 0.41 \times n^{-0.43} \times (L_{track} [m] \times P[atm])^{-0.32} \left[\frac{S_{dN_{cl}/dx}}{(dN_{cl}/dx)} = (d_{cl} \times L_{track})^{-1/2}\right]
$$

from *Walenta parameterization (1980)* from *Poisson distribution*

truncated mean cut (70-80%) reduces the amount of collected information  $n = 112$  and a 2m track at 1 atm give

$$
\sigma \approx 4.3\%
$$

Increasing P to 2 atm improves resolution by  $20\%$  ( $\sigma$ )  $\approx$ 3.4%) but at a considerable cost of multiple scattering contribution to momentum and angular resolutions.



*dE/dx dNcl/dx*

$$
\frac{S_{dN_{cl}/dx}}{(dN_{cl}/dx)} = (d_{cl} \times L_{track})^{-1/2}
$$



 $\delta_d$  = 12.5/cm for He/iC<sub>4</sub>H<sub>10</sub>=90/10 and a 2m track give

$$
\sigma \thickapprox 2.0\%
$$

A small increment of  $iC_4H_{10}$  from 10% to 20%  $(\delta_{\rm d} = 20/\text{cm})$  improves resolution by 20% (σ  $\approx$ 1.6%) at only a reasonable cost of multiple scattering contribution to momentum and angular resolutions.

*Moreover, C.C. allows can improve the spatial resolution < 100 μm for 8 mm drift cells in He based gas mixtures* 

#### 07/30/2020

## Silicon detectors for precision measurements:

- vertex detector/inner tracker (VTX)
- silicon medium and outer tracker
- silicon wrapper (SET)

+ design of the mechanical structure (light-weight staves)



## Silicon wrapper **INFN** Genua

- ➢ Low-Gain Avalanche Diodes (LGADs) are n-in-p silicon sensors
- Operated in low-gain regime ( $\sim$  20) controlled by the external bias
- Critical electric field  $E_c \sim 20 30 \text{ V/}\mu\text{m} \rightarrow \text{gain}$  layer region
- $\triangleright$  Detector ion resistive substrate (RSD) suitable for the si-Wrapper, combining tracking and TOF

The p<sup>+</sup> dopant concentration of the gain implant gets reduced by irradiation and LGADs loose their multiplication power above ~  $3.10^{15}$  n<sub>eq</sub>/cm<sup>2</sup>

An innovative design of the gain implant has been designed to extend signal multiplication up to  $\sim 10^{17}$  n<sub>eq</sub>/cm<sup>2</sup>

 $\rightarrow$  Compensated LGAD

 $\rightarrow$  A 3 years project has been accepted for funding by AIDAinnova as Blue Sky R&D to investigate and develop the compensated LGAD design



## Silicon wrapper **INFN** Genua

#### **Risoluzione Spaziale**

- dipende da molti fattori: pitch, geometria degli elettrodi rumore dell'elettronica, digitalizzazione del segnale, algoritmo di ricostruzione...
- Si possono raggiungere risoluzioni pari a circa il 3% del pitch degli elettrodi

#### **Risoluzione Temporale**

- I sensori RSD mantengono le eccellenti caratteristiche di risoluzione temporale degli LGAD
- misura ottenuta dalla combinazione dei segnali distribuiti;
- contributo aggiuntivo dal ritardo di propagazione del segnale;
- ottima uniformità osservata sull'area attiva
- Test su fascio su geometrie della prima produzione hanno mostrato risoluzioni di 40-45 ps (~20 ps da test con laser)



## The **µ-RWELL**: the detector architecture

The  $\mu$ -RWELL is composed of only two elements: the u-RMELL PCB and the cathode

The u-RWELL PCB, the core of the detector, is realized by coupling:

- 1. a WELL patterned kapton foil as amplification stage
- 2. aresistivelayer(\*) for discharge suppression:
	- **i.** Single resistive layer (SRL) <100 kHz/cm<sup>2</sup>: single resistive layer → surface resistivity  $~100$  MO/ $~$  (SHiP; CepC, Novosisbirsk, EIC, HIEPA)
	- ii. Double resistive layer  $(DRL) > 1$  MHz/cm<sup>2</sup>: for LHCb-Muon upgrade
- 3. a standard readout PCB

 $(*)$  DLC = Diamond Like Carbon highly mechanical & chemical resistant



#### **G. Bencivenni et al., 2015\_JINST\_10\_P02008**



## The  $\mu$ -RWELL: principle of operation

Applying a suitable voltage between the top Cu-layer and the DLC the WELL acts as a multiplication channell for the ionization produced in the conversion/drift gas gap.

#### Introduction of the resistive stage:

Pros: suppression of the transition from streamer to spark

 $\rightarrow$  Spark amplitude reduction

Cons: reduction of the capability to stand high particle fluxes. But an appropriate grounding schemes of the resistive layer solves this problem







Comparison between the current drawn by a single GEM and a μ-RWELL at various **gas gain.**

The black spikes are the sparks in the detectors, clearly dumped in the μ-RWELL for higher gains

## The  $\mu$ -RWELL: overview of performance

### Results with 2017 testbeam data at PSI lab



## Plans for 2022/203

R&D for the 2022 foreseens the production of  $\mu$ -RWELL with X-Y readout  $\rightarrow$ beamtest In October 2022 (SPS-H8-CERN)

### Detector layouts 2D



These layouts allow to operate at lower gain with respect to the GEM detectors in «COMPASS»

Easy production technlogy for both layouts. Bi-dimensional space resolution to be verified with Beam Test

## Technology transfer with ELTOS/CERN: flow chart

**DLC sputtering with new INFN- CERN machine @ CERN**



**Step 1:** producing  $\mu$ -RWELL\_PCB -with top patterned (pad/strip) -without bottom patterned

**Step 2:** DLC patterning -in ELTOS with BRUSHING-machine

> **Step 3:** DLC foil gluing on PCB -double 106-prepreg  $(-2x50 \Box m)$  thick) (already used in ELTOS) -pre-smoothing  $+$  106-prepreg ( $-50 \mu m$  thick) -single 1080-prepreg  $(-75 \mu m)$  thick)

**Step 4:** top copper patterning

> **Step 5:** Kapton etching on small PCB





## Technology transfer with ELTOS/CERN: flow chart



### **Responsibility:**

- Detector design (GERBER);
- Link with ELTOS
- Link with CERN-Rui
- Quality Control detector
- DLC Machine managment (>2023)



### **Responsibility:**

- PCB RWELL production
- Cathode production
- DLC+PCB RWELL coupling



### **Responsibility:**

- PCB RWELL finalization
- **Hot Electrical Cleaning**
- Detector closure

